

YZPST-Copper clad ceramic plate series

覆铜陶瓷板 | Copper clad ceramic plate

物理性质 | Physical Property

铜层剥离强度 Copper layer peeling strength	≥ 6N/mm@50mm/min
适用温度 Temperature	Depending on the usage environment, it is suitable for temperatures ranging from -55 °C to 850 °C
弯曲强度 (陶瓷) bending strength	> 400N/ > 450N/
表面粗糙度 Surface roughness	Ra ≤ 3um
热膨胀系数 (陶瓷) Thermal expansion coefficient	6.9ppm/K@40-400℃ 7.8ppm/K@40-800℃
热导率 Thermal conductivity	24W/m.K@25℃
电阻率 resistivity	> 10 ¹⁴ Ω.cm@25℃ > 10 ¹⁰ Ω.cm@300℃
介电常数 dielectric constant	9.8±10%@1MHz
介电损耗 Dielectric loss	≤ 0.0003@23℃, 1MHz
绝缘强度 (直流) Dielectric Strength	AC,2.5KVMS,60HZ,1Min
铜层导电率 Copper layer conductivity	58*10 ⁶ S/m

产品选型 | Product Selection

铜厚度 (mm) Copper thickness (mm)	Al2O3 厚度 (mm) Al2O3 thickness (mm)
0.25	0.25、0.32、0.38、0.635、0.76、1.0
0.3	0.32、0.38、0.635、0.76、1.0
0.4	0.32、0.35、0.38、0.635、0.76、1.0

Copper coated ceramic plate:

It is an electronic base material made by directly sintering copper boxes on ceramic surfaces, which has good thermal cycling properties: high mechanical strength, high thermal conductivity, high insulation properties, and high current carrying capacity.

Suitable for packaging materials of high-power IGBT modules, thyristor modules, and semiconductor refrigeration and heating devices.

surface appearance:
1.Double sided copper 2.Single sided nickel 3.Double sided tin copper surface with OSP anti oxide film for soldering.

Product quality control:

Adopting fully automatic detection, automatic marking, and X-RAY non-destructive testing equipment for control.

产品外形图 | Product Outline Drawing

